



## Material Content Data Sheet



Sales Product Name	SAK-XC2268N-40F80L AA			Issued		29. August 2013		
MA#	MA001059314							
Package	PG-LQFP-100-8			Weight*		753.33 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	28.688	3.81	3.81	38081	38081
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.01		91	
	non noble metal	zinc	7440-66-6	0.275	0.04		365	
	non noble metal	iron	7439-89-6	5.501	0.73		7302	
	non noble metal	copper	7440-50-8	223.351	29.65	30.43	296485	304243
wire	noble metal	gold	7440-57-5	2.532	0.34	0.34	3361	3361
encapsulation	organic material	carbon black	1333-86-4	2.362	0.31		3136	
	plastics	epoxy resin	-	63.786	8.47		84672	
	inorganic material	silicondioxide	60676-86-0	406.340	53.93	62.71	539392	627200
leadfinish	non noble metal	tin	7440-31-5	9.288	1.23	1.23	12330	12330
plating	noble metal	silver	7440-22-4	2.495	0.33	0.33	3312	3312
glue	plastics	epoxy resin	-	2.161	0.29		2868	
	noble metal	silver	7440-22-4	6.482	0.86	1.15	8605	11473
*deviation	< 10%	Sum in total:			100,00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com